

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	2.5	A
T_{OP}	Operating Temperature	-40 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

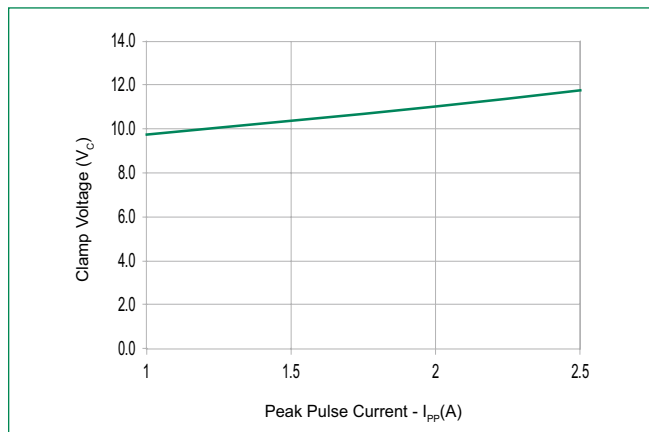
Electrical Characteristics - ($T_{OP}=25^{\circ}C$)

Parameter	Test Conditions	Min	Typ	Max	Units
Input Capacitance	@ $V_R = 0V$, $f = 3GHz$		0.30		pF
Breakdown Voltage	V_{BR} @ $I_T=1mA$		8.2		V
Reverse Working Voltage	$I_R \leq 1\mu A$			7.0	V
Reverse Leakage Current	I_L @ $V_{RWM}=5.0V$		0.02	1	μA
Dynamic Resistance ²	TLP, $t_p=100ns$, I/O to GND		0.58		Ω
Clamping Voltage ¹	V_{CL} @ $I_{PP}=2.5A$		11.8		V
ESD Withstand Voltage ¹	IEC 61000-4-2 (Contact)	± 22			kV
	IEC 61000-4-2 (Air)	± 22			

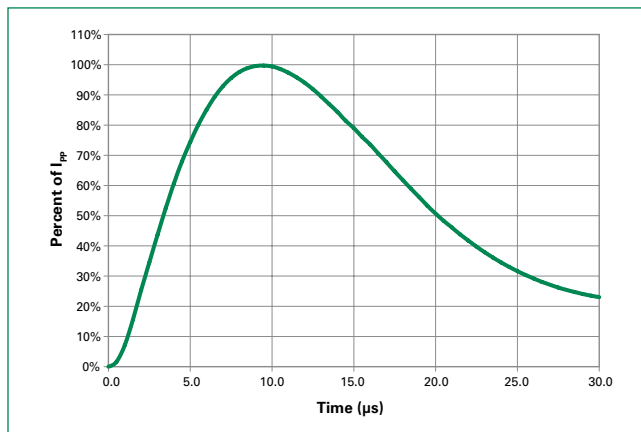
Note:

- Parameter is guaranteed by design and/or component characterization.
- Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window $t_1=70ns$ to $t_2=90ns$

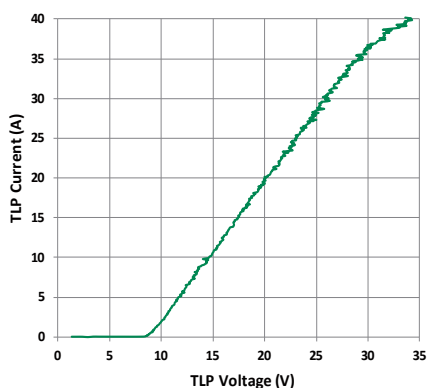
Clamping Voltage vs I_{PP}



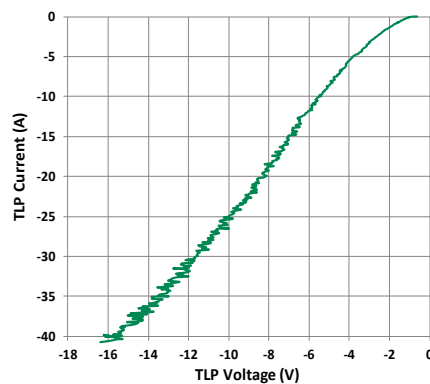
8/20 μs Pulse Waveform



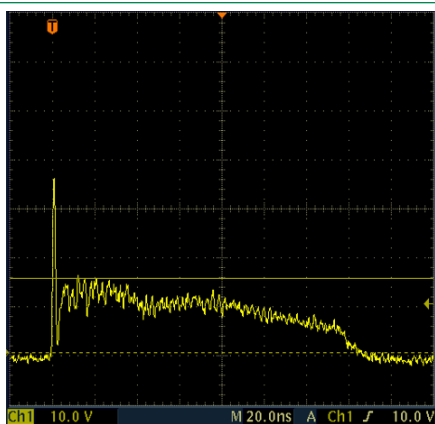
Positive Transmission Line Pulsing (TLP) Plot



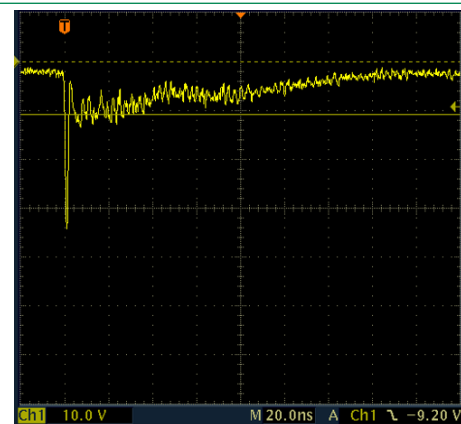
Negative Transmission Line Pulsing (TLP) Plot



IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage

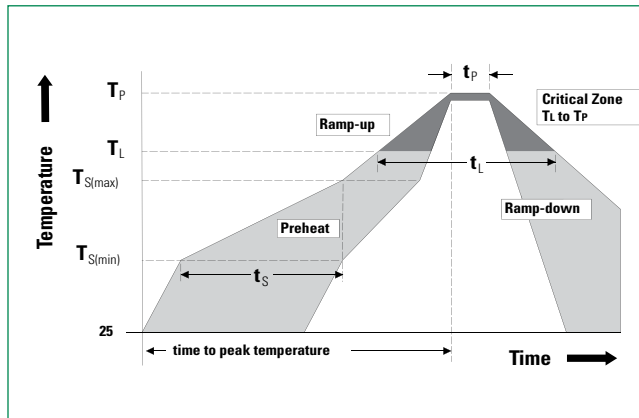


IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage

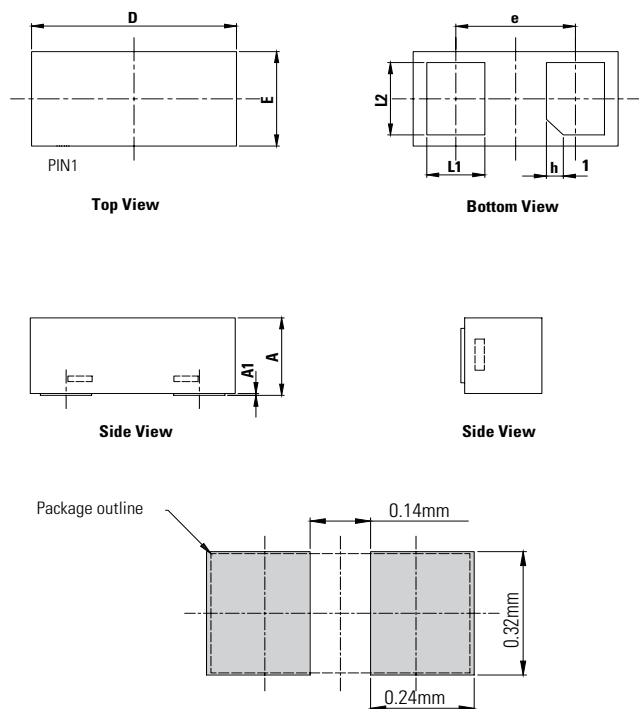


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_P)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C

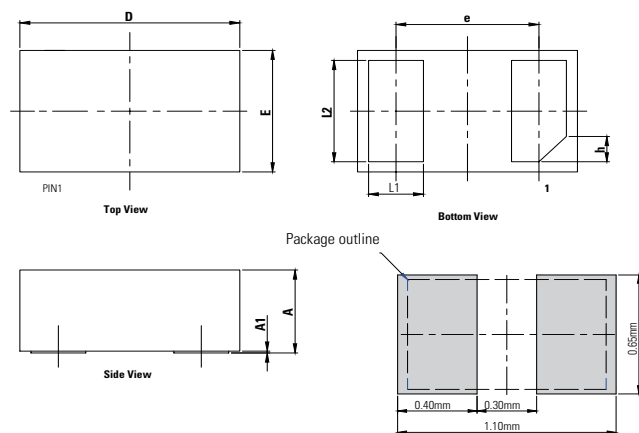


Package Dimensions — 0201 DFN



Symbol	Millimeters			Inches		
	Min	Max	Max	Min	Min	Max
A	0.23	0.28	0.33	0.009	0.011	0.013
A1	0.00	0.02	0.05	0.000	0.001	0.002
L1	0.12	0.18	0.24	0.005	0.007	0.009
L2	0.18	0.24	0.30	0.007	0.009	0.012
D	0.55	0.60	0.65	0.022	0.024	0.026
E	0.25	0.30	0.35	0.010	0.012	0.014
e	0.35 (BSC)			0.014 (BSC)		
h	0.05 (x 45°)			0.002 (x 45°)		

Package Dimensions — SOD882



Recommended soldering pad layout

Symbol	Millimeters			Inches		
	Min	Max	Max	Min	Min	Max
A	0.40	0.45	0.50	0.016	0.018	0.020
A1	0.00	0.02	0.05	0.000	0.001	0.002
L1	0.20	0.25	0.30	0.008	0.010	0.012
L2	0.45	0.50	0.55	0.018	0.020	0.022
D	0.90	1.00	1.10	0.035	0.039	0.043
E	0.50	0.60	0.70	0.020	0.024	0.028
e	0.65 (BSC)			0.026 (BSC)		
h	0.125 (x 45°)			0.005 (x 45°)		

Part Numbering System

SP 3530 -01 U T G

TVS Diode Arrays (SPA® Diodes)

Series

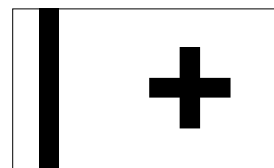
Number of Channels

Package

U: 0201 DFN
E: SOD882

G= Green
T= Tape & Reel

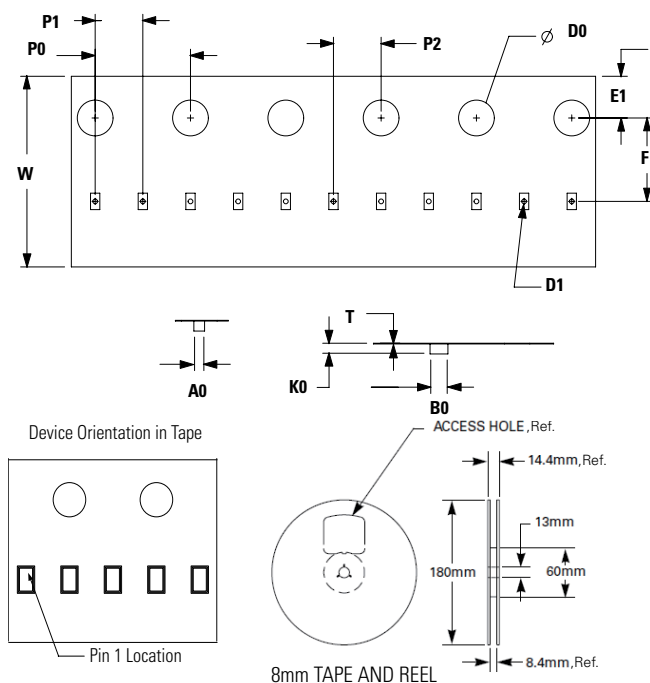
Part Marking System



Ordering Information

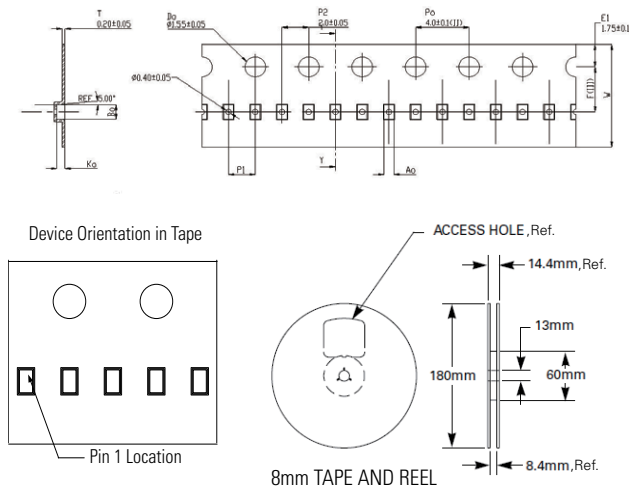
Part Number	Package	Min. Order Qty.
SP3530-01UTG	0201 DFN	15000
SP3530-01ETG	SOD882	10000

Embossed Carrier Tape & Reel Specification — 0201 DFN



Symbol	Millimeters
A0	0.33 min/0.41 max
B0	0.63 min/0.71 max
D0	Ø 1.50 +0.10/-0
D1	Ø 0.20 +/- 0.05
E1	1.75+/-0.10
F	3.50+/-0.05
K0	0.30 min/0.39 max
P0	4.00+/-0.10
P1	2.00+/-0.10
P2	2.00+/-0.05
W	8.00+0.30/-0.10
T	0.13 min/0.25 max

Embossed Carrier Tape & Reel Specification — SOD882



Symbol	Millimeters
A0	0.70+/-0.045
B0	1.10+/-0.045
K0	0.65+/-0.045
F	3.50+/-0.05
P1	2.00+/-0.10
W	8.00 + 0.30 -0.10